

## 103 年 9 月 通過 學術審查

年 級：博六（97 碩入，98 上直升）

### 著作列表

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#### Journal Papers

1. Chia-Hung Lin, **Jian-Jhih Kuo\***, Bing-Hong Liu, and Ming-Jer Tsai, “GPS-free, boundary-recognition-free, and reliable double-ruling-based information brokerage scheme in wireless sensor networks,” IEEE Transactions on Computers, vol. 61, no. 6, pp. 885-898, 2012.

#### Conference Papers

1. **Jian-Jhih Kuo\***, Hsiu-Hsien Yang, and Ming-Jer Tsai, “Optimal approximation algorithm of virtual machine placement for data latency minimization in cloud systems,” IEEE INFOCOM 2014, pp. 1303-1311, Toronto, Canada, April 2014.
2. Chia-Hung Lin, **Jian-Jhih Kuo\***, and Ming-Jer Tsai, “Reliable GPS-free double-ruling-based information brokerage in wireless sensor networks,” IEEE INFOCOM 2010 (mini-conference), pp. 1427-1435, San Diego, California, USA, March 2010.
3. Yao-Jen Tang, **Jian-Jhih Kuo\***, and Ming-Jer Tsai, “Double- ruling-based location-free data replication and retrieval scheme in mobile ad hoc networks,” IEEE ICCCN 2014, pp. 781-788, Shanghai, China, August 2014.

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年 級：博五 (99 上博士班入學)

### 著作列表

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#### Journal Papers

1. **Po-Yang Hsu**, Hsien-Te Chen and Tingting Hwang, “Stacking Signal TSV for Thermal Dissipation in Global Routing for 3-D IC”, IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD), Vol.33, Issue 7, pp. 1031-1042, 2014. (EI/SCI, Impact factor = 1.203)

#### Conference Papers

1. **Po-Yang Hsu**, Hsien-Te Chen and Tingting Hwang, “Stacking Signal TSV for Thermal Dissipation in Global Routing for 3-D IC”, IEEE/ACM Asia and South Pacific Design Automation Conference (ASP-DAC), pp. 699-704, 2013. (97/311)
2. **Po-Yang Hsu**, Tingting Hwang, “Thread-criticality Aware Dynamic Cache Reconfiguration in Multi-core System”, IEEE/ACM International Conference on Computer-Aided Design (ICCAD), 413-420, 2013. (92/354)
3. **Po-Yang Hsu**, Pei-Lan Lin, Tingting Hwang, “Compaction-free Compressed Cache for High Performance Multi-core System”, IEEE/ACM International Conference on Computer-Aided Design (ICCAD), 2014. (Accepted)